



NOTES:

1. Mfr. Texas Instruments
2. Die size .105 x .075 ± .005

FIGURE 2
DIE CONFIGURATION

3.2 Electrical Requirements

Each die shall be tested by probing and meet the performance requirement at 25 degrees C as specified in Table 1 and be capable of meeting the requirements specified for test temperatures of -55 and +125 degrees C.

TABLE I
ELECTRICAL CHARACTERISTICS

switching characteristics, $V_{CC} = 5 V$, $T_A = 25^\circ C$

PARAMETER [†]	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS	MIN	TYP	MAX	UNIT
f_{max}			$C_L = 15 pF$, $R_L = 280 \Omega$	40	70		MHz
t_{PLH}	Clock	Ripple carry			14	25	ns
t_{PHL}					17	25	
t_{PLH}	Clock	Any Q			8	15	ns
t_{PHL}					10	15	
t_{PLH}	Enable T	Ripple carry			10	15	ns
t_{PHL}					10	15	

[†] f_{max} = maximum clock frequency
 t_{PLH} = propagation delay time, low-to-high-level output
 t_{PHL} = propagation delay time, high-to-low-level output

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